Special Issue

The Advanced Application of Intelligent Sensor & Artificial intelligence (AI)

Message from the Guest Editors

Artificial intelligence (AI) has facilitated the development of human society. Its use in practice in recent years has proven the effectiveness of this technology for solving varieties of problems in industry, manufacturing, the medical field, etc. Indeed, in the last few decades, we have witnessed remarkable progress in sensor manufacturing and application. Applying artificial intelligence technology into sensors can make hardware systems more intelligent, thus accelerating the progress of practical application. Therefore, there is a pressing demand for new scalable and highly performing approaches that can cope with this explosion in the field of intelligent sensors and artificial intelligence (AI). We believe this Special Issue will serve as a timely collection of research on advantaged applications of intelligent sensors and artificial intelligence (AI). Please clink the following link for the more details:

https://www.mdpi.com/journal/applsci/special_issues/intelligent_sensor

Guest Editors

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Deadline for manuscript submissions

closed (20 June 2023)

About the Journal

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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